

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Toshiyuki HIROTA	09/20/2011
Takakazu KIYOMURA	09/20/2011
Yuichiro MOROZUMI	09/20/2011
Shingo HISHIYA	09/20/2011

RECEIVING PARTY DATA

Name:	Elpida Memory, Inc.
Street Address:	2-1, Yaesu 2-chome
City:	Chuo-ku, Tokyo
State/Country:	JAPAN
Postal Code:	104-0028

Name:	Tokyo Electron Limited
Street Address:	3-1, Akasaka 5-chome
City:	Minato-ku, Tokyo
State/Country:	JAPAN
Postal Code:	107-6325

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13245515

CORRESPONDENCE DATA

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 Correspondent Name: SUGHRUE MION, PLLC

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ATTORNEY DOCKET NUMBER: Q126865

NAME OF SUBMITTER: Kyle H. Compton, New Applic. Specialist

Total Attachments: 2
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Assignment

Whereas, I/We, Toshiyuki HIROTA and Takakazu KIYOMURA, both of Tokyo, ofcx
Yuichiro MOROZUMI and Shingo HISHIYA, both of Yamanashi, all of Japan

hereinafter called assignor(s), have invented certain improvements in
SEMICONDUCTOR DEVICE, METHOD OF MANUFACTURING THE SAME AND
ADSORPTION SITE BLOCKING ATOMIC LAYER DEPOSITION METHOD

and executed an application for Letters Patent of the United States of America therefor on
September 20, 2011; and

Whereas, Elpida Memory, Inc.
2-1, Yaesu 2-chome, Chuo-ku, Tokyo 104-0028 Japan,
and
Tokyo Electron Limited
3-1, Akasaka 5-chome, Minato-ku, Tokyo 107-6325 Japan

(assignee), desires to acquire the entire right, title, and interest in the application and invention, and to any United States patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,

I/We, the above named assignor(s), hereby sell, assign and transfer to the above named assignee, its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America, including the right to claim priority under 35 U.S.C. §119, and I/we request the Director - U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee, its successors and assigns; and I/we will execute without further consideration all papers deemed necessary by the assignee in connection with the United States application when called upon to do so by the assignee.

I/We hereby authorize and request our attorneys SUGHRUE MION, PLLC of 2100 Pennsylvania Avenue, NW, Washington, DC 20037-3213 to insert here in parentheses (Application number 13/245,515 and Confirmation number 4418, filed September 26, 2011) the filing date and application number of said application when known.

Date: Sept. 20, 2011 Toshiyuki Hirota
s/ Toshiyuki HIROTA
Date: Sept. 20, 2011 Takakazu Kiyomura
s/ Takakazu KIYOMURA
Date: _____
s/ Yuichiro MOROZUMI
Date: _____
s/ Shingo HISHIYA

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. §261)

Witness: Shoji Spul

Assignment

Whereas, I/We, Toshiyuki HIROTA and Takakazu KIYOMURA, both of Tokyo, ofxx
Yuichiro MOROZUMI and Shingo HISHIYA, both of Yamanashi, all of Japan

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Date: _____
s/ Toshiyuki HIROTA
Date: _____
s/ Takakazu KIYOMURA
Date: Sept. 20, 2011 Yuichiro Morozumi
s/ Yuichiro MOROZUMI
Date: Sept. 20, 2011 Shingo Hishiya
s/ Shingo HISHIYA

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. §261)

Witness: Katsuhige Harada
Mitsuo Mizutani